

2019 SCHEDULE OF HIR WORKSHOPS

1. [Heterogeneous Integration Roadmap Symposium](#) Milpitas, CA 2/21/2019
2. [SEMICON China](#), Shanghai, China CSTIC 3/18-19/2019
3. [EuroSimE](#) Hannover, Germany 3/24-27/2019
4. [ICEP](#) Niigata 4/17-20/2019
5. [ECIO](#) Ghent, Belgium 4/24-26/2019
6. [Advanced Semiconductor Manufacturing Conference](#) 5/6-9/195.
7. [ECTC & ITherm](#) Las Vegas, NV 5/28-31/2019
8. [VLSI Symposium](#) 6/9/2019
9. [NordPac](#) Denmark 6/11-13/2019
10. Palo Alto Meeting 7/7/2019
11. [SEMICON West](#) San Francisco, CA 7/9-11/2019
12. [ICEPT](#) Hong Kong 8/11-15/2019
13. [Electronics Packaging Symposium](#) Niskayuna, NY 9/5-6/2019
14. HIR Workshop with EPS Japan, JIEP & SEMI Japan Tokyo, Japan TBD
15. [SEMICON Taiwan](#) 9/18-20/2019
16. [IMAPS](#) Boston, MA 10/1-3/2019
17. [INTERPACK 2019](#) Anaheim, CA 10/7-9/2019
18. [IMPACT](#) Taiwan 10/24-26/2019
19. [SEMICON Europa](#) Germany 11/12-15/2019
20. [ICSJ](#) Kyoto, Japan 11/18-20/2019
21. [EPTC](#) Singapore, 12/4-6/2019
22. [IEDM](#), CA 12/9-11/2019